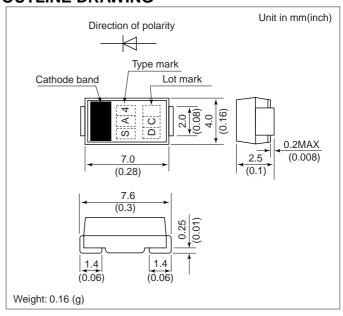
DSM3MA

FEATURES

- For general purpose
- High heat-resistant due to glass passivation.

OUTLINE DRAWING



ABSOLUTE MAXIMUM RATINGS

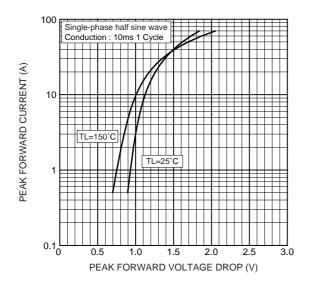
Items	Type		DSM3MA1	DSM3MA2	DSM3MA4				
Repetitive Peak Reverse Voltage	V_{RRM}	V	100	200	400				
Average Forward Current	$I_{F(AV)}$	А	3.0 (Single-phase half sine wave 180° conduction TL = 108°C)						
Surge(Non-Repetitive) Forward Current	I _{FSM}	Α	80(Without PIV, 10ms, conduction Tj = 40°C start)						
I ² t Limit Value	l ² t	A ² s	25.6(Time = 2 ~ 10ms, I = RMS value)						
Operating Junction Temperature	T _j	°C	-40 ~ +150						
Storage Temperature	T _{sta}	°C	-40 ~ +150						

CHARACTERISTICS(T_L=25°C)

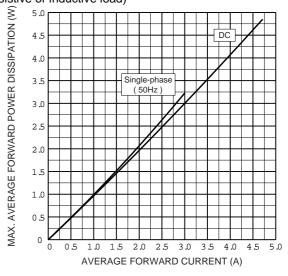
Items	Symbols	Units	Min.	Тур.	Max.	Test Conditions	
Peak Reverse Current	I _{RRM}	μΑ	-	-	20	DSM3MA1,2	Rated V _{RRM}
					10	DSM3MA4	
Peak Forward Voltage	V_{FM}	V	_	-	1.0	I _{FM} =3.0Ap, Single-phase half sine wave 1 cycle	
Steady State Thermal Impedance	$R_{th(j-a)}$	°C/W	_	I	80 13	On glass-epox Soldering land	ti substrate (□ 50mm) I (□ 10mm)

DSM3MA

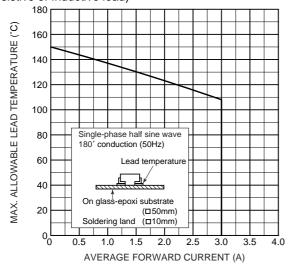
Forward characteristics



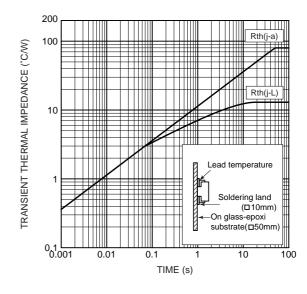
Max. average forward power dissipation (Resistive or inductive load)



Max. allowable lead temperature (Resistive or inductive load)



Transient thermal impedance



HITACHI POWER SEMICONDUCTORS

Notices

- 1. The information given herein, including the specifications and dimensions, is subject to change without prior notice to improve product characteristics. Before ordering, purchasers are adviced to contact Hitachi sales department for the latest version of this data sheets.
- 2.Please be sure to read "Precautions for Safe Use and Notices" in the individual brochure before use.
- 3.In cases where extremely high reliability is required(such as use in nuclear power control, aerospace and aviation, traffic equipment, life-support-related medical equipment, fuel control equipment and various kinds of safety equipment), safety should be ensured by using semiconductor devices that feature assured safety or by means of users' fail-safe precautions or other arrangement. Or consult Hitachi's sales department staff.
- 4.In no event shall Hitachi be liable for any damages that may result from an accident or any other cause during operation of the user's units according to this data sheets. Hitachi assumes no responsibility for any intellectual property claims or any other problems that may result from applications of information, products or circuits described in this data sheets.
- 5.In no event shall Hitachi be liable for any failure in a semiconductor device or any secondary damage resulting from use at a value exceeding the absolute maximum rating.
- 6.No license is granted by this data sheets under any patents or other rights of any third party or Hitachi, Ltd.
- 7. This data sheets may not be reproduced or duplicated, in any form, in whole or in part, without the expressed written permission of Hitachi, Ltd.
- 8. The products (technologies) described in this data sheets are not to be provided to any party whose purpose in their application will hinder maintenance of international peace and safety not are they to be applied to that purpose by their direct purchasers or any third party. When exporting these products (technologies), the necessary procedures are to be taken in accordance with related laws and regulations.
- For inquiries relating to the products, please contact nearest overseas representatives which is located "Inquiry" portion on the top page of a home page.

Hitachi power semiconductor home page address http://www.hitachi.co.jp/pse